

ABSTRACT

In order to mount a semiconductor element of a small electrode pitch, an inner lead portion of a lead frame is made thin and narrow to reduce a pitch. Even for a semiconductor element in which an electrode arrangement pitch is smaller than the conventional pitch can be mounted by flip chip bonding, the number of components such as a wire is reduced, and a possibility of wire cutting or the like caused by vibration or the like during semiconductor device assembling is reduced. A fine inner lead formation scheduled area of a conductor plate is half-etched to make a plate thickness smaller than that in a peripheral area. Then, the fine inner lead formation scheduled area is patterned to form a fine inner lead portion. Especially, a width of a tip of the fine inner lead portion is set smaller than those of a middle inner lead portion and an outer lead portion.